

- Q2
B
- (c) patterning via lines or via grids in the dielectric layer;
 - (d) filling the patterned via lines or via grids with a conductive material, such as a metal, and preferably tungsten or copper; and
 - (e) applying a metal bond pad on top of the dielectric layer and the filled via lines or via grids.
-

B
13

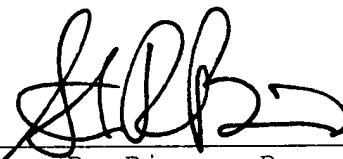
11. (Amended) A method as claimed in claim 8, wherein the via lines or lines of metal are applied in the form of a grid.

REMARKS

The claims have been amended in order to reformat the claims to delete all multiple dependencies prior to calculation of the filing fee and place the instant application in standard U.S. format.

Entry of this amendment prior to calculating the filing fee is respectfully requested.

Respectfully submitted,

By 
Steven R. Biren, Reg. 26,531
Attorney
(914) 333-9630
April 10, 2001